	951	Search Text 257/666	DB USPAT; US-PGPUB; EPO; JPO;	Time stamp 2004/08/05 17:13
2	951			
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		257/667	USPAT;	2004/08/05 17:21
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1			DERWENT;	
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3	2334	237/000	US-PGPUB;	2004/08/03 17.40
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4	1063	257/324	USPAT;	2004/08/05 17:51
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			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
5	842	257/635	USPAT;	2004/08/05 17:58
			US-PGPUB;	·
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			DERWENT;	
		057/750	IBM_TDB	0004/00/05 10 05
6	4668	257/758	USPAT;	2004/08/05 18:31
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			DERWENT; IBM TDB	
7	2650	257/700	USPAT;	2004/08/05 18:55
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			DERWENT;	
			IBM TDB	
8	2132	438/118	USPAT;	2004/08/05 19:12
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			IBM_TDB	
9	1646	438/123	USPAT;	2004/08/05 19:14
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			DERWENT; IBM TDB	
	105	'van der waal' and 257/\$.ccls.	USPAT;	2003/03/26 13:23
	100	van der waar and 201/9.0018.	US-PGPUB;	2003/03/20 13:23
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-	225	'van der waal' and 438/\$.ccls.	USPĀT;	2004/08/05 16:35
			US-PGPUB;	
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			IBM_TDB	0000455455
-	42	latex and 257/\$.ccls.	USPAT;	2003/03/25 18:10
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			DERWENT;	
_	53	latex and 438/\$.ccls.	IBM_TDB USPAT;	2002/07/11 10:23
	23	Tates and 400/9.0015.	US-PGPUB;	2002/01/11 10:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	156	self-vulcanizing latex and (copper adj	USPAT;	2003/03/26 11:25
		layer) and interconnect and 257/\$.ccls.	US-PGPUB;	
	!		EPO; JPO;	
			DERWENT;	
			IBM_TDB	

Search History 8/5/04 7:45:13 PM Page 1

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-	644		USPAT;	2002/07/09 11:06
		(copper layer) and polyimide and	US-PGPUB;	
		257/\$.ccls.	EPO; JPO; DERWENT;	
	·		IBM TDB	
_	36	interconnect and (multichip adj module)	USPAT;	2002/07/09 14:20
		and (copper adj layer) and polyimide and	US-PGPUB;	
		257/\$.ccls.	EPO; JPO;	
			DERWENT;	
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_	379	257/75\$.ccls. and polymer	USPAT; US-PGPUB;	2002/07/11 10:24
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			DERWENT; IBM TDB	
_	10	(dielectric) and (silicon adj based adj	USPAT;	2002/07/12 09:28
		adhesive)	US-PGPUB;	
	İ		EPO; JPO;	
			DERWENT;	
	74	430/0	IBM_TDB USPAT;	2003/03/26 08:06
-	/4	438/\$.ccls. and (latex)	US-PGPUB;	2003/03/26 08:06
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			DERWENT;	
			IBM_TDB	
-	21	257/\$.ccls. and (polymer WITH latex)	USPAT;	2003/10/27 15:25
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			DERWENT;	
			IBM TDB	
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			DERWENT; IBM TDB	
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			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	10	420/6 cala and /latau with	IBM_TDB	2002/10/20 10:11
-	40	438/\$.ccls. and (latex with particle)	USPAT; US-PGPUB;	2003/10/28 18:11
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			DERWENT;	
	•		IBM_TDB	
-	86	438/\$.ccls. and (dielectric near3 rough)	USPAT;	2003/10/29 08:57
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	•		EPO; JPO; DERWENT;	
			IBM TDB	
-	98	257/\$.ccls. and (dielectric near3 rough)	USPAT;	2003/10/29 09:10
	1		US-PGPUB;	
			EPO; JPO;	
		<b>b</b>	DERWENT; IBM TDB	
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